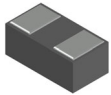


MECHANICAL CASE OUTLINE

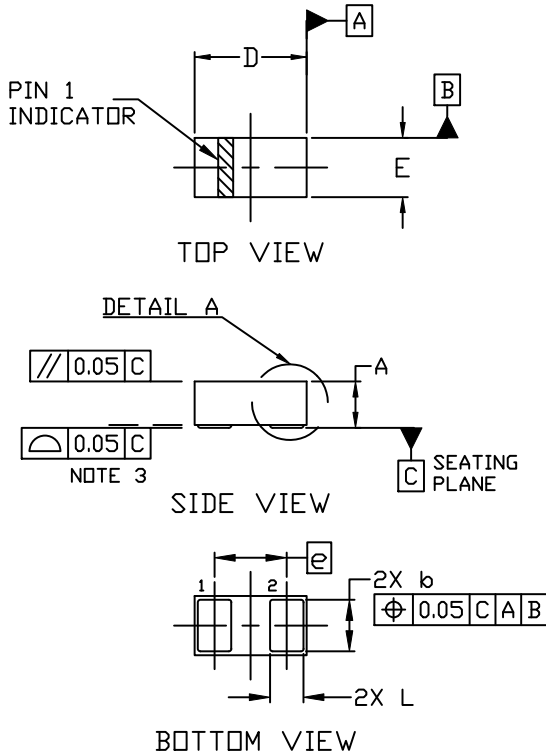
PACKAGE DIMENSIONS

ON Semiconductor®



DSN2, 0.435x0.23, 0.28P
CASE 152BB
ISSUE A

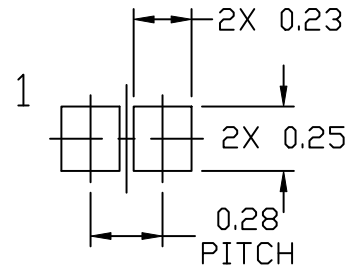
DATE 10 MAR 2021



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO ALL PADS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.165	0.180	0.195
A1	0.008	0.011	0.014
A2	0.157	0.169	0.181
b	0.192	0.200	0.208
D	0.415	0.435	0.455
E	0.210	0.230	0.250
e	0.28 BSC		
L	0.122	0.130	0.138



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	DSN2, 0.435X0.23, 0.28P	PAGE 1 OF 1

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